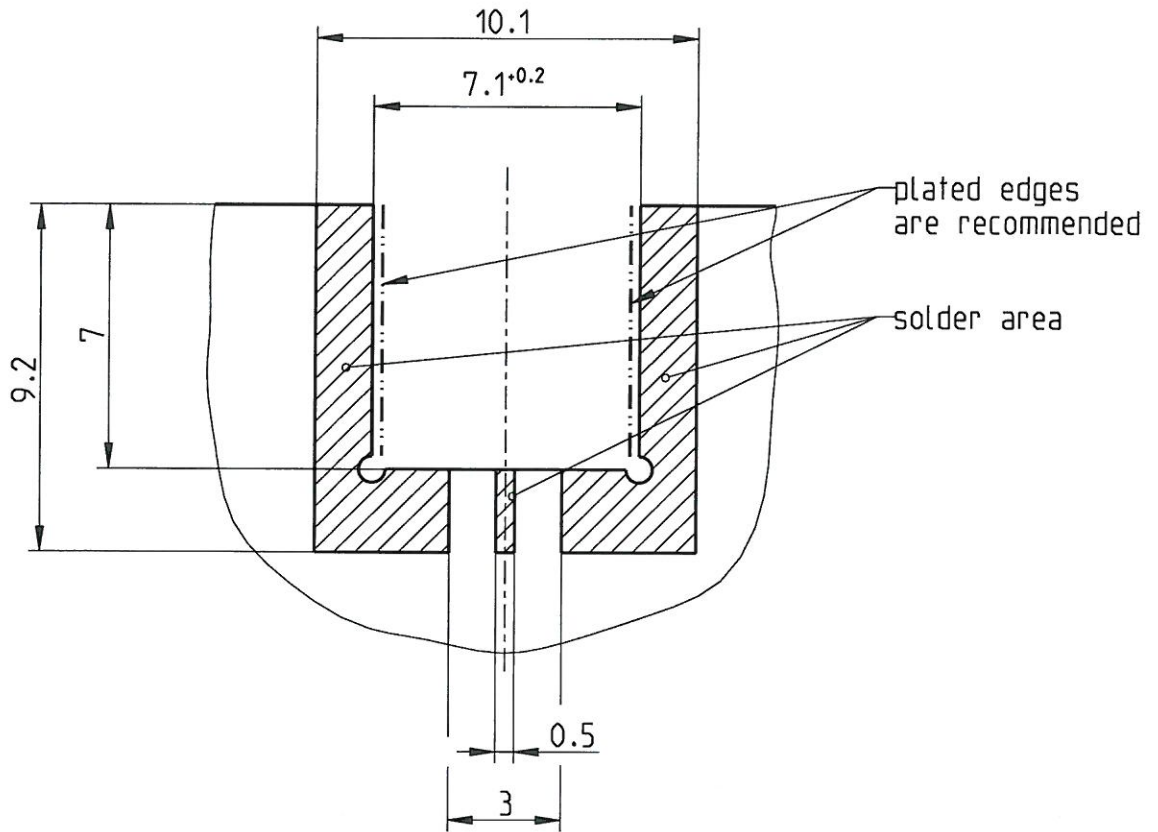


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Leiterplatten-Layout
 PCB layout
 B 210



A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.

Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.

In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

fuer diese technische Unterlage behalten
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Formblatt: TCC-FB-05-PL-A1-Einzelteil
 Platz: 13/000-conf/03/03/03
 Datum: 10.04.2006
 Version: 1.1

ISO-Projektion
 Methode E
 -METRIC-

Rosenberger Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER				general tolerance ISO 2768 m-H				RN 006-01 dimensions <0,5 and symmetry				scale: 5:1		weight(g): surface(mm ²):	
				date drawn 10.04.2006 check. 10.4.06 appr. 10.4.06				name A_Nobis				title: Leiterplatten-Layout PCB layout			
				dimensioning incl. finish								drawing-no.: MB_210		sheet: 1	
a00 06-s175		A_Nobis		10.04.2006		distribu- tion to:		FE X AZ . QSM . RMT . . .		drawing-no.: MB_210		of: 1			
rev. change-no		name		date		distribu- tion to:		FE X AZ . QSM . RMT . . .		drawing-no.: MB_210		remarks: .			